CV of Giovanni Verzellesi

Giovanni Verzellesi
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Education and academic appointments

Born in Reggio Emilia in 1964, MS in Electrical Engineering (cum laude) from the University of Bologna in 1989, visiting graduate student at the University of California, Santa Barbara, USA, in 1993-94, PhD in Electronics from the University of Padova in 1994.

Full Professor of Electronics at the University of Modena and Reggio Emilia since 2006.

Formerly, Associate Professor of Electronics from 2000 to 2006 and Research Associate from 1994 to 2000.

Research

Modelling, simulation and characterization of semiconductor devices and sensors. Current research interests: wide bandgap semiconductor devices for power applications, GaN-based LEDs, Gallium-Oxide based UVC photodetectors, diamond-based transistors.

Past research topics: InGaAs MOSFETs for post-11-nm CMOS technology nodes: device simulation, modelling/optimization, statistical variability, GaAs and InP field-effect transistors for RF applications, Si and SiC radiation detectors (X-ray, nuclear radiation), Si optical and chemical sensors, impact-ionization effects and measurement/modelling of parasitic resistances in Si bipolar transistors.

Publications

More than 130 articles in international journals (including more than 50 articles in IEEE journals), >140 papers in proceedings of international conferences, 4 book chapters. See http://scholar.google.it/citations?user=VqyA9LgAAAAJ&hl=en&oi=ao for complete list of publications, citations, and h-index.

Editorial activity

Senior Member, Institute of Electrical and Electronic Engineers (IEEE), since 2008. Editor, IEEE Transactions on Electron Devices (subject area: Compound Semiconductor Devices), 2017-2020. Member of the Editorial Board, Micromachines, 2019-today. Special Issue Editor, Micromachines (ISSN 2072-666X), section D: Materials and Processing, "Wide Bandgap Based Devices: Design, Fabrication and Applications, Volume II", Aug. 2021.cGuest Associate Editor, Frontier in Physics: Radiation Detectors and Imaging, "Physics-based Numerical Modeling and Design of Particle Detectors", 2021. TPC member of: IEEE International Electron Devices Meeting (IEDM), 2004-2005; IEEE International Reliability Physics Symposium (IRPS), 2010-2012; European Symposium on Reliability of Electron Devices, Failure Physics and Analysis (ESREF), 2010-2025; Expert Evaluation & Control of Compound Semiconductor Materials & Technologies (EXMATEC), 2012;

European Solid-State Device Conference (ESSDERC), 2014. *Steering committee* member of European Workshop on Heterostructure Technology (HETECH), 2003-2013. G*eneral co-chair* of HETECH in 2008, *publications co-chair* of ESSDERC in 2014.

Department and university service

Prorector, University of Modena and Reggio Emilia, 2019-2025.
Rector's Delegate for Third Mission, University of Modena and Reggio Emilia, 2019-2025.
Vice Head, Department of Sciences and Methods for Engineering, 2012-2018.
Vice Dean, Faculty of Engineering, Reggio Emilia, 2010-2012.
Chair, Undergraduate and graduate programs in Electronic Engineering, 2006-2008.